TPS60300, TPS60301, TPS60302, TPS60303 SINGLE-CELL TO 3.0-V/3.3-V, 20-mA DUAL OUTPUT, HIGH-EFFICIENCY CHARGE PUMP SLVS302A – DECEMBER 2000 – REVISED MARCH 2001

features

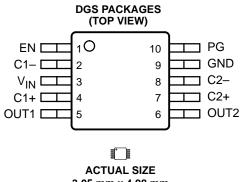
- Regulated 3-V or 3.3-V Output Voltage With up to 20-mA Output Current From a 0.9-V to 1.8-V Input Voltage Range
- High Power Conversion Efficiency (up to 90%) Over a Wide Output Current Range, Optimized for 1.2-V Battery Voltage
- Additional Output With 2 Times V_{IN} (OUT1)
- Device Quiescent Current Less Than 35 μA
- Supervisor Included; Open Drain or Push-Pull Power Good Output
- No Inductors Required/Low EMI
- Only Five Small, 1-µF Ceramic Capacitors Required
- Load Isolated From Battery During Shutdown
- Microsmall 10-Pin MSOP Package

description

The TPS6030x step-up, regulated charge pumps generate a 3-V \pm 4% or 3.3-V \pm 4% output voltage from a 0.9-V to 1.8-V input voltage (one alkaline, NiCd, or NiMH battery).

applications

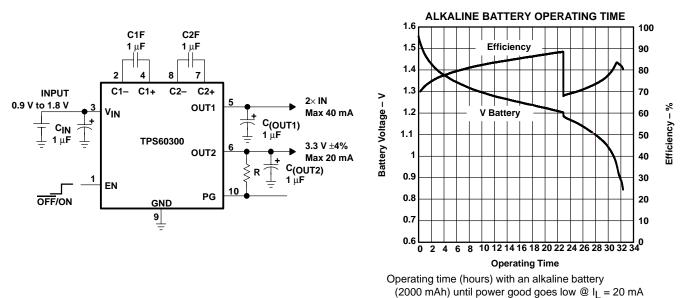
- Pagers
- Battery-Powered Toys
- Portable Measurement Instruments
- Home Automation Products
- Medical Instruments (Like Hearing Instruments)
- Metering Applications Using MSP430 Microcontroller
- Portable Smart Card Readers



3,05 mm x 4,98 mm

Only five small $1-\mu F$ ceramic capacitors are required to build a complete high efficiency dc/dc charge pump converter. To achieve the high efficiency over a wide input voltage range, the charge pump automatically selects between a 3x or 4x conversion mode.

typical application circuit





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



Copyright © 2001, Texas Instruments Incorporated

SLVS302A - DECEMBER 2000 - REVISED MARCH 2001

description (continued)

Output 1 (OUT1) can deliver a maximum of 40 mA, from a 1-V input, with output 2 (OUT2) not loaded. OUT2 can deliver a maximum of 20 mA, from a 1-V input, with OUT1 not loaded. Both outputs can be loaded in the same time, but the total output current of the first voltage doubler must not exceed 40 mA. For example, the load at OUT1 is 20 mA and the load at output 2 is 10 mA.

The devices operate in the newly developed LinSkip mode. In this operating mode, the device switches seamlessly from the power saving, pulse-skip mode at light loads, to the low-noise, constant-frequency linear-regulation mode, once the output current exceeds the device-specific output current threshold.

A power-good function supervises the output voltage of OUT2 and can be used for power up and power down sequencing. Power good (PG) is offered as either open-drain or push-pull output.

PART NUMBER [†]	MARKING DGS PACKAGE	OUTPUT CURRENT 1 [mA] [‡]	OUTPUT CURRENT 2 [mA] [§]	OUTPUT VOLTAGE 1 [V]	OUTPUT VOLTAGE 2 [V]	FEATURE
TPS60300DGS	ALF	40	20	2 x V _{IN}	3.3	Open-drain power-good output
TPS60301DGS	ALG	40	20	2 x V _{IN}	3.0	Open-drain power-good output
TPS60302DGS	ALI	40	20	2 x V _{IN}	3.3	Push-pull power-good output
TPS60303DGS	ALK	40	20	2 x V _{IN}	3.0	Push-pull power-good output

AVAILABLE OPTIONS

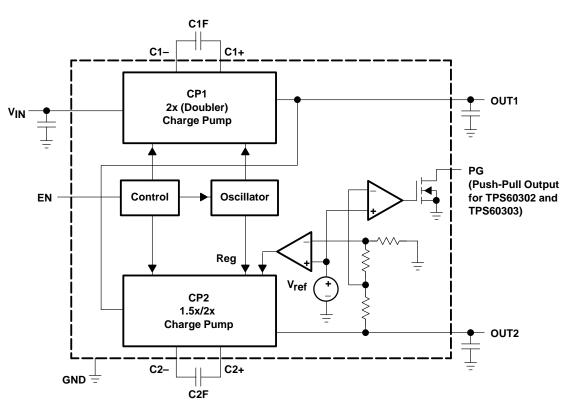
[†] The DGS package is available taped and reeled. Add R suffix to device type (e.g. TPS60300DGSR) to order quantities of 2500 devices per reel. [‡] If OUT2 is not loaded

§ If OUT1 is not loaded



SLVS302A - DECEMBER 2000 - REVISED MARCH 2001

TPS60300 and TPS60301 functional block diagram



Terminal Functions

TERMINAL			DECORIDETION			
NAME	NO.	I/O	DESCRIPTION			
C1+	4		Positive terminal of the flying capacitor C1F			
C1–	2		Negative terminal of the flying capacitor C1F			
C2+	7		Positive terminal of the flying capacitor C2F			
C2–	8		Negative terminal of the flying capacitor C2F			
EN	1	I	Device-enable input – EN = Low disables the device. Output and input are isolated in shutdown mode. – EN = High enables the device.			
GND	9		GROUND			
OUT1	5	0	$2 \times V_{IN}$ power output. Bypass OUT1 to GND with the output filter capacitor C _(OUT1) .			
OUT2	6	0	Regulated 3.3-V power output (TPS60300, TPS60302) or 3-V power output (TPS60301, TPS60303), respectively Bypass OUT2 to GND with the output filter capacitor C _(OUT2) .			
PG	10	0	Power good detector output. As soon as the voltage on OUT2 reaches about 98% of its nominal value this pin goes high. Open drain output on TPS60300 and TPS60301. A pullup resistor should be connected between PG and OUT1 or OUT2. Push-pull output stage on TPS60302 and TPS60303			
VIN	3	I	Supply input. Bypass VIN to GND with a ≥ 1 -µF capacitor.			



SLVS302A - DECEMBER 2000 - REVISED MARCH 2001

detailed description

operating principle

The TPS6030x charge pumps are voltage quadruplers that provide a regulated 3.3-V or 3.0-V output from a 0.9-V to 1.8-V input. They deliver a maximum load current of 20 mA. Designed specifically for space critical battery powered applications, the complete converter requires only five external capacitors and enables the design to use low-cost, small-sized, $1-\mu$ F ceramic capacitors. The TPS6030x circuits consist of an oscillator, a voltage reference, an internal resistive feedback circuit, an error amplifier, two charge pump stages with MOSFET switches, a shutdown/start-up circuit, and a control circuit.

shutdown

Driving EN low disables the converter. This disables all internal circuits, reducing input current to only $0.05 \,\mu$ A. Leakage current drawn from the output pins OUT1 and OUT2 is a maximum of 1 μ A. The device exits shutdown once EN is set high (see start-up procedure described below). The typical no-load, start-up time is 400 μ s. When the device is disabled, the load is isolated from the input. This is an important feature in battery operated products because it extends the battery shelf life.

start-up procedure

The device is enabled when EN is set from logic low to logic high. CP1 will first enter a dc start-up mode during which the capacitor on OUT1 is charged up to about V_{IN} . After that, it starts switching to boost the voltage further up to about two times V_{IN} . CP2 will then follow and charge up the capacitor on OUT2 to about the voltage on OUT1, after that, it will also start switching and boost up the voltage to its nominal value. EN must not exceed the highest voltage applied to the device.

NOTE:

During start-up with $V_{OUT} = 0$ V, the highest voltage is the input voltage.

power-good detector

The power-good output is an open-drain output on the TPS60300 and TPS60301 or a push-pull output on the TPS60302 and TPS60303. The PG-output pulls low when the output of OUT2 is out of regulation. When the output rises to within 98% of regulation, the power-good output goes active high. In shutdown, power-good is pulled low. In normal operation, an external pullup resistor with the TPS60300 and TPS60301 is typically used to connect the PG pin to VOUT. The resistor should be in the 100-k Ω to 1-M Ω range. If the PG output is not used, it should remain unconnected. Output current at PG (TPS60302, TPS60303) will reduce maximum output current at OUT2.



SLVS302A - DECEMBER 2000 - REVISED MARCH 2001

absolute maximum ratings over operating free-air temperature (unless otherwise noted)[†]

Input voltage, V_I (IN to GND) (see Note 1) Output voltage, V_O (OUT1,OUT2, EN, PG to GND) (see Note 1) Voltage, (C1+ to GND) Voltage, (C1- to GND, C2- to GND) Voltage, (C2+ to GND) Continuous power dissipation Output current, I _O (OUT1)	-0.3 V to 3.6 V -0.3 V to V _{O(OUT1)} + 0.3 V -0.3 V to V _{IN} + 0.3 V -0.3 V to V _{O(OUT2)} + 0.3 V See Dissipation Rating Table
Output current, I _O (OUT2)	40 mA

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The voltage at EN and PG can exceed IN up to the maximum rated voltage without increasing the leakage current drawn by these pins.

PACKAGE	T _A <25°C POWER RATING	DERATING FACTOR ABOVE T _A = 25°C	T _A = 70°C POWER RATING	T _A = 85°C POWER RATING		
DGS	424 mW	3.4 mW/°C	271 mW	220 mW		
IOTE. The thermal resistance junction to ambient of the DGS package is $R_{T,1}$, $\mu = 204^{\circ}CM$						

DISSIPATION RATING TABLE

The thermal resistance junction to ambient of the DGS package is $R_{TH-JA} = 294^{\circ}C/W$. NOTE:

recommended operating conditions

	MIN	NOM	MAX	UNIT
Input voltage, VI	0.9		1.8	V
Output current (OUT2), I _{O(OUT2)}			20	mA
Output current (OUT1), IO(OUT1)			40	mA
Input capacitor, CI	1			μF
Flying capacitors, C1F, C2F		1		μF
Output capacitors, C _{O(1)} , C _{O(2)}	1			μF
Operating junction temperature, TJ	-40		125	°C



SLVS302A – DECEMBER 2000 – REVISED MARCH 2001

electrical characteristics at $C_{IN} = C1F = C2F = C_{(OUT1)} = C_{(OUT2)} = 1 \ \mu F, T_C = -40^{\circ}C \text{ to } 85^{\circ}C, V_{IN} = 1.0 \text{ V}, V_{(EN)} = V_{IN}$ (unless otherwise noted)

	PARAMETER		TEST CON	IDITIONS	MIN	ΤΥΡ	MAX	UNIT	
VIN	Supply voltage range				0.9		1.8	V	
			$V_{IN} \ge 1.1 \text{ V}, I_{O(OU)}$ $I_{(PG,1)} = 0 \text{ mA}$	T2) = 0 mA,	40				
IO(OUT1)	Maximum output current for TPS	60300,	V _{IN} = 0.9 V, I _{O(OU} I(PG,1) = 0 mA	T2) = 0 mA,	20				
1	TPS60302		$V_{IN} \ge 1.1 \text{ V}, I_{O(OU)}$ $I_{(PG,1)} = 0 \text{ mA}$	T1) = 0 mA,	20			mA	
IO(OUT2)			V _{IN} = 0.9 V, I _{O(OU} I _(PG,1) = 0 mA	T1) = 0 mA,	10				
			$V_{IN} \ge 1.1 \text{ V}, I_O(OU)$ I(PG,1) = 0 mA	JT2) = 0 mA,	40				
IO(OUT1)	Maximum output current for TPS TPS60303	60301,	V _{IN} = 0.9 V, I _{O(OU} I _(PG,1) = 0 mA	T2) = 0 mA,	20			mA	
	17 300303		$\begin{array}{l} V_{IN} \geq 1.0 \ V, I_{O(OU)} \\ I_{(PG,1)} = 0 \ mA \end{array}$	T1) = 0 mA,	20			mA	
IO(OUT2)			V _{IN} = 0.9 V, I _{O(OU} I(PG,1) = 0 mA	Γ1) = 0 mA,	12				
νοιοιτα	O(OUT2) Output voltage for TPS60300, TPS60302		1.1 V < V _{IN} < 1.8 V, I _O (OUT1) = 0 mA 0 < I _O (OUT2) < 20 m	nA	3.17	3.30	3.43	v	
0(0012)			0.9 V < V _{IN} < 1.1 V, I _{O(OUT1)} = 0 mA, I _O	D(OUT2) < 10 mA	3.17	3.30	3.43		
VO(OUT2)	2) Output voltage for TPS60301, TPS60303		$1.0 V < V_{IN} < 1.8 V,$ $I_O(OUT1) = 0 mA,$ $0 < I_O(OUT2) < 20 m$	nA	2.88	3	3.12	v	
0(0012)	,,		V _{IN} > 1.65 V, I _{O(OL} 25 μA < I _{O(OUT2}) <	JT1) = 0 mA, 20 mA	2.88	3	3.15		
V	Output voltaga rinnla	OUT2	IO(OUT2) = 20 mA,	$I_O(OUT1) = 0 mA$		20		m\/-	
V _{P-P}	Output voltage ripple	OUT1	IO(OUT1) = 40 mA,	$I_{O(OUT2)} = 0 \text{ mA}$		40		mV _{P-I}	
lq	Quiescent current (no-load input	current)	$I_{O(OUT)} = 0 \text{ mA},$	V _{IN} = 1.8 V		35	70	μΑ	
			V _{IN} = 1.8 V, See Note 2	V _(EN) = 0 V,		0.05	2.5		
I(SD)	Shutdown supply current		$V_{IN} = 1.8 V,$ $T_{C} = 25^{\circ}C,$	V _(EN) = 0 V, See Note 2			0.5	μΑ	
fosc	Internal switching frequency				470	700	900	kHz	
VIL(EN)	EN input low voltage		$V_{\mbox{IN}}$ = 0.9 V to 1.8 V				$0.3 \times V_{IN}$	V	
VIH(EN)	EN input high voltage		$V_{\mbox{IN}}$ = 0.9 V to 1.8 V		$0.7 \times V_{\text{IN}}$			V	
l _{lkg}	EN input leakage current		V _(EN) = 0 V or V _{IN} o V _O (OUT1)	or VO(OUT2) or		0.01	0.1	μA	
	LinSkip switching threshold		V _{IN} = 1.25 V			7.5		mA	
	Short circuit current		V _{IN} = 1.8 V	$\frac{V_{O(OUT2)} = 0 V}{V_{O(OUT1)} = 0 V}$	5 2	20 80	50 150	mA	
	Output leakage current	OUT2	VO(OUT1) = 3 V, VO(OUT2) = nomina			00	100	μA	

NOTE 2: OUT1 not loaded. If OUT1 is connected to GND via a resistor, leakage current will be increased.



SLVS302A - DECEMBER 2000 - REVISED MARCH 2001

electrical characteristics at $C_{IN} = C1F = C2F = C_{(OUT1)} = C_{(OUT2)} = 1 \ \mu F, T_C = -40^{\circ}C \text{ to } 85^{\circ}C, V_{IN} = 1.0 \text{ V}, V_{(EN)} = V_{IN}$ (unless otherwise noted) (continued)

PARAMETER	TEST CONDITIONS	MIN TYP	MAX	UNIT
Output load regulation	$V_{IN} = 1.25 \text{ V}, _C = 25^{\circ}\text{C}$ 2 mA < I _{O(OUT2)} < 20 mA	0.1		%/mA
Output line regulation	$1.0 \text{ V} < \text{V}_{IN} < 1.65 \text{ V};$ $T_C = 25^{\circ}C,$ $I_O(OUT) = 10 \text{ mA}$	0.75		%/V
No-load start-up time		400		μs
Impedance of first charge pump stage		4		Ω
	V _{IN} ≥ 1.1 V	165		
Start-up performance at OUT2 (minimum start-up load resistance)	$V_{IN} \ge 1.0 V$	330		Ω
start up load resistance)	V _{IN} = 0.9 V	1000		1
Start-up performance at OUT1 (minimum start-up load resistance)	V _{IN} = 1.0 V	500		Ω

electrical characteristics for power good comparator of devices TPS6030x at $T_C = -40^{\circ}C$ to 85°C, $V_{IN} = 1.0$ V and $V_{(EN)} = V_{IN}$ (unless otherwise noted)

	PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V _(PG)	Power good trip voltage		VO ramping positive		V _O – 2%	VO	V
V _{hys}	Power good trip voltage hysteresis		VO ramping negative		10%		
VOL	O Power good output voltage low		V _O = 0 V, I _(PG) = 1.6 mA			0.3	V
	5	TPS60300	V _O = 3.3 V, V _(PG) = 3.3 V		0.01	0.1	
l _{lkg}	Power good leakage current	TPS60301	V _O = 3.0 V, V _(PG) = 3.0 V		0.01	0.1	μA
.,	B	TPS60302		3			.,
VOH	Power good output voltage high	TPS60303	I _(PG) = –5 mA	2.7			V
IO(PG,1)	Output current at power good (source)	TPS60302, TPS60303		-5			mA
IO(PG,0)	Output current at power good (sink)	All devices	V _(PG) = 0 V	1.6			mA
R(PG,1)	Output resistance at power good	TPS60302, TPS60303	V _(PG) = V _{O(OUT2)}		15		Ω
R(PG,0)		All devices	V(PG) = 0 V		100		Ω



TPS60300, TPS60301, TPS60302, TPS60303 SINGLE-CELL TO 3.0-V/3.3-V, 20-mA DUAL OUTPUT, HIGH-EFFICIENCY CHARGE PUMP SLVS302A – DECEMBER 2000 – REVISED MARCH 2001

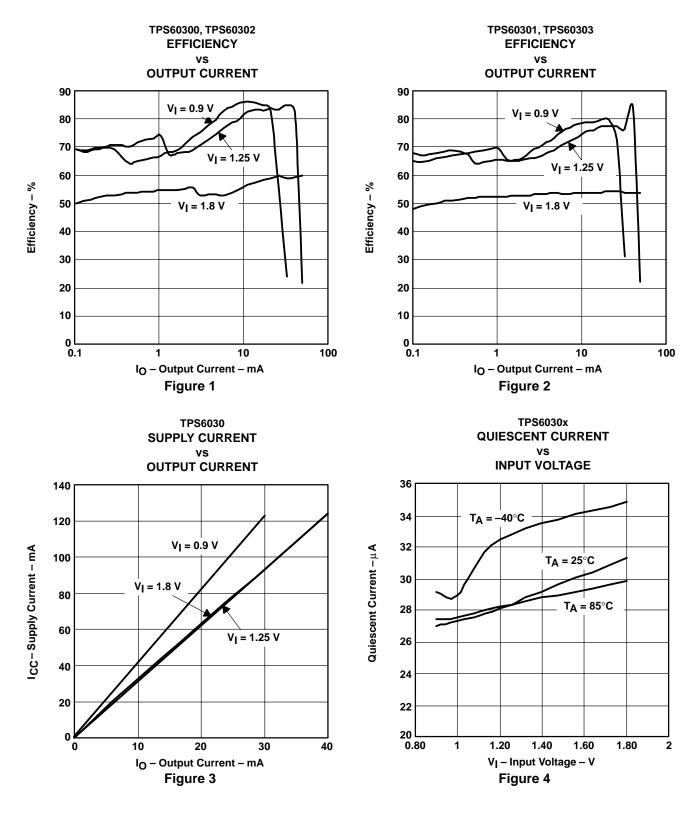
TYPICAL CHARACTERISTICS

Table of Graphs

			FIGURE
η	Efficiency	vs Output current	1, 2
IS	Supply current	vs Output current	3
lQ	Quiescent current	vs Input voltage	4
VO(OUT2)	Output voltage at OUT2	vs Output current	5, 6
VO(OUT1)	Output voltage at OUT1	vs Output current at 25°C, VIN = 0.9 V, 1.1 V, 1.25 V, 1.4 V, 1.6 V, 1.8 V	7
VO(OUT2)	Output voltage at OUT2	vs Input voltage	8, 9
VO(OUT1)	Output voltage at OUT1	vs Input voltage	10
VO(OUT2)	Output voltage at OUT2	vs Free-air temperature	11, 12
VO(OUT2)	Output voltage ripple at OUT2		13
	Minimum input voltage	vs Output current for TPS60301, TPS60303	14, 15
	Start-up timing	Enable, OUT1 no load, OUT2 at full load	16
	Switching frequency	vs Input voltage	17
	Load transient response	V _{IN} = 1.25 V, I _{O(OUT2)} = 2 mA 18 mA 2 mA, OUT1: no load	18
	Line transient response		19



SLVS302A - DECEMBER 2000 - REVISED MARCH 2001



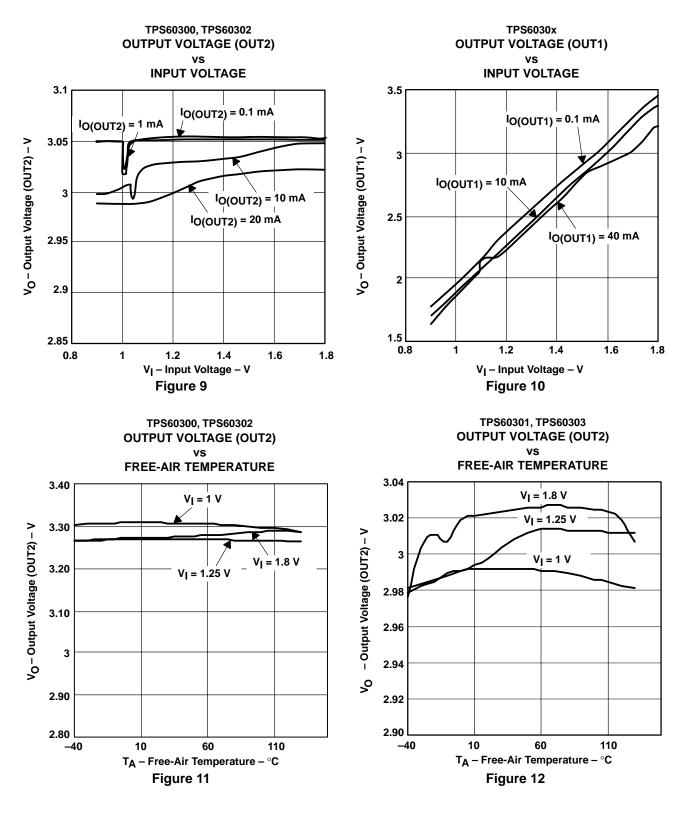


SLVS302A - DECEMBER 2000 - REVISED MARCH 2001

TPS60300, TPS60302 TPS60301, TPS60303 **OUTPUT VOLTAGE (OUT2) OUTPUT VOLTAGE (OUT2)** vs vs **OUTPUT CURRENT (OUT2) OUTPUT CURRENT (OUT2)** 3.4 3.2 Vj = 1.8 V 3.1 Vj = 1.25 V VI = 1.8 V V_O – Output Voltage (OUT2) – V V_O – Output Voltage (OUT2) – V 3.2 Vj = 1.25 V 3 $V_{I} = 1.1 V$ $V_{I} = 1.1 V$ 2.9 3 $V_{I} = 0.9 V$ VI = 0.9 V 2.8 2.8 2.7 2.6 2.6 0 10 20 30 40 10 20 30 40 0 IO - Output Current (OUT2) - mA IO – Output Current (OUT2) – mA Figure 5 Figure 6 TPS60300, TPS60302 TPS60300, TPS60302 **OUTPUT VOLTAGE (OUT2) OUTPUT VOLTAGE (OUT1)** vs vs **INPUT VOLTAGE OUTPUT CURRENT (OUT1)** 3.35 4 3.3 V_O- Output Voltage (OUT2) - V 3.5 Vj = 1.8 V V_O – Output Voltage (OUT1) – V IO(OUT2) = 0.1 mA 3.25 IO(OUT2) = 1 mA Vj = 1.6 V IO(OUT2) = 10 mA 3 3.2 VI = 1.4 V IO(OUT2) = 20 mA 3.15 2.5 V_I = 1.25 V 3.1 $V_{I} = 1.1 V$ 2 3.05 VI = 0.9 V 1.5 3 0 20 40 60 0.8 1 1.2 1.4 1.6 1.8 IO - Output Current (OUT1) - mA V_I – Input Voltage – V Figure 7 Figure 8

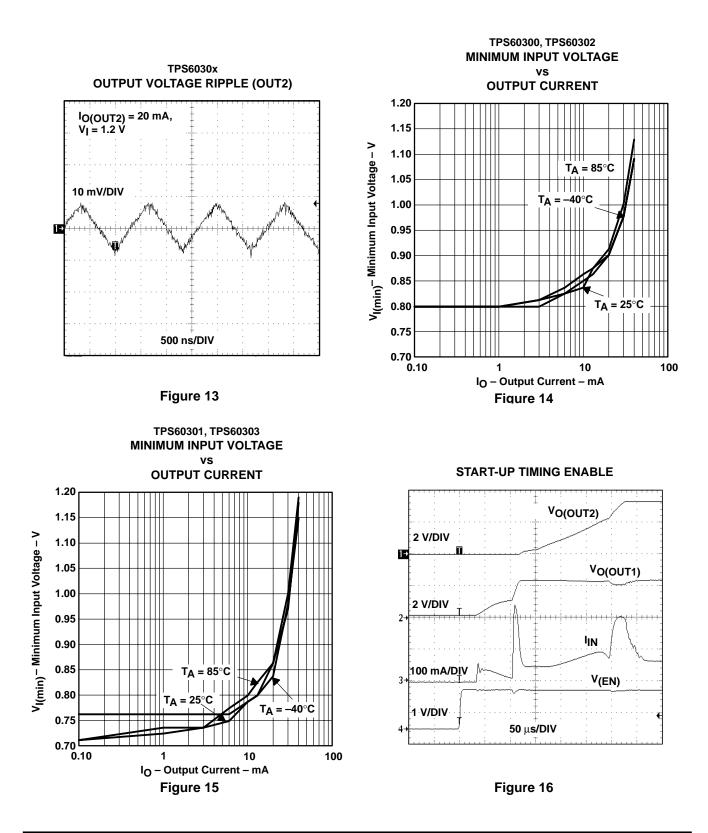


SLVS302A - DECEMBER 2000 - REVISED MARCH 2001



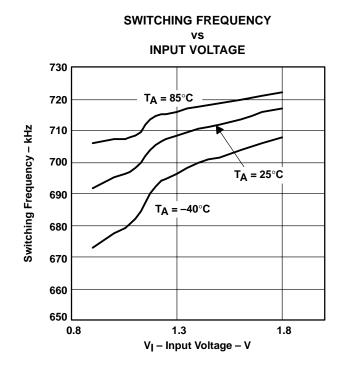


SLVS302A - DECEMBER 2000 - REVISED MARCH 2001





SLVS302A - DECEMBER 2000 - REVISED MARCH 2001



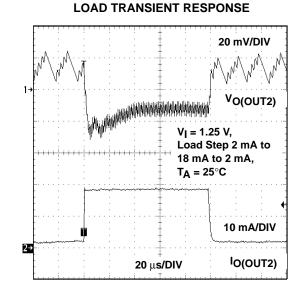


Figure 17



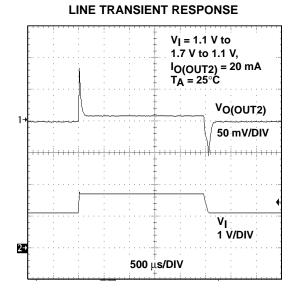


Figure 19



SLVS302A - DECEMBER 2000 - REVISED MARCH 2001

APPLICATION INFORMATION

design procedure

capacitor selection

The TPS6030x devices require only five external capacitors. Their values are closely linked to the required output current and the output noise and ripple requirements. It is possible to only use $1-\mu F$ capacitors of the same type.

The input capacitor improves system efficiency by reducing the input impedance and stabilizing the input current.

The minimum required capacitance of the output capacitor (C_O) that can be selected is 1 μ F. Depending on the maximum allowed output ripple voltage, larger values can be chosen. Table 1 shows capacitor values recommended for low output voltage ripple operation. A recommendation is given for the smallest size.

Table 1. Recommended Capacitor Values for Low Output Voltage Ripple Operation

	VIN IO(OUT2) [V] [mA]		^I O(OUT2) [μF]		^C ΟUT [μF]	VP_P [mV] · @ 20 mA/	
	[•]	[CERAMIC	CERAMIC	CERAMIC	VIN = 1.1 V	
ĺ	0.91.8	020	1	1	1	16	
ſ	0.91.8	020	1	1	2.2	10	
	0.91.8	020	1	1	10 // 0.1	6	

Table 2. Recommended Capacitors

MANUFACTURER	PART NUMBER	SIZE	CAPACITANCE	TYPE
Taiyo Yuden	UMK212BJ104MG	0805	0.1 μF	Ceramic
	LMK212BJ105KG	0805	1 μF	Ceramic
	LMK212BJ225MG	0805	2.2 μF	Ceramic
	JMK316BJ475KL	1206	4.7 μF	Ceramic
AVX	0805ZC105KAT2A	0805	1 μF	Ceramic
	1206ZC225KAT2A	1206	2.2 μF	Ceramic

Table 3 lists the manufacturers of recommended capacitors. However, ceramic capacitors will provide the lowest output voltage ripple due to their typically lower ESR.

Table 3. Recommended	Capacitor	Manufacturers
----------------------	-----------	---------------

MANUFACTURER	CAPACITOR TYPE	INTERNET
Taiyo Yuden	X7R/X5R ceramic	www.t-yuden.com
AVX	X7R/X5R ceramic	www.avxcorp.com
Vishay	X7R/X5R ceramic	www.vishay.com
Kemet	X7R/X5R ceramic	www.kemet.com
TDK	X7R/X5R ceramic	www.component.tdk.com



SLVS302A - DECEMBER 2000 - REVISED MARCH 2001

APPLICATION INFORMATION

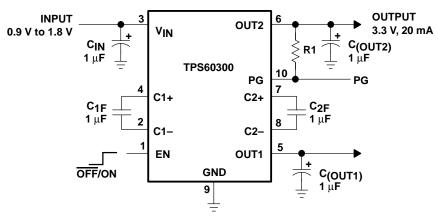


Figure 20. Typical Operating Circuit

For the maximum output current and best performance, five ceramic capacitors of 1 µF are recommended. For lower currents or higher allowed output voltage ripple, other capacitors can be used. It is recommended that the input and output capacitors have a minimum value of 1 µF. This value is necessary to assure a stable operation of the system due to the linear mode. With flying capacitors lower than 1 μ F, the maximum output power will decrease. This means that the device will work in the linear mode with lower output currents.

output filter design

The power-good output is capable of driving light loads up to 5 mA (see Figure 21). Therefore, the output resistance of the power-good pin, in addition with an output capacitor, can be used as an RC-filter.

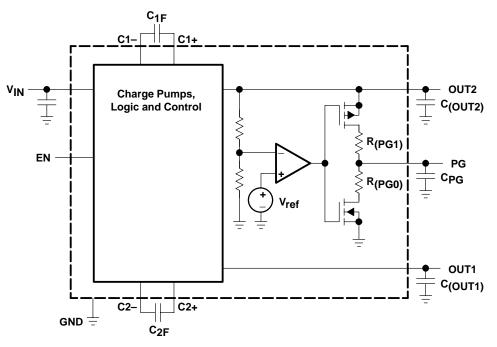


Figure 21. TPS60302, TPS60303 Push-Pull Power-Good Output-Stage as Filtered Supply



SLVS302A - DECEMBER 2000 - REVISED MARCH 2001

design procedure (continued)

Due to R_(PG,1), an output filter can easily be formed with an output capacitor (C_{PG}). Cut-off frequency is given by:

$$f_{\rm C} = \frac{1}{2\pi R_{\rm (PG,1)}^{\rm C}(\rm PG)} \tag{1}$$

and ratio V_{OUT}/V_{IN} is:
$$\left| \frac{V(PG,1)}{V_O(OUT2)} \right| = \frac{1}{\sqrt{1 + \left(2\pi f R_{(PG,1)}C_{(PG)}\right)^2}}$$
 (2)

with $R_{(PG,1)} = 15 \Omega$, $C_{(PG)} = 0.1 \mu F$ and f = 600 kHz (at nominal switching frequency)

$$\left|\frac{V(PG,1)}{V_{O(OUT2)}}\right| = 0.175$$

Load current sourced by power-good output reduces maximum output current at OUT2. During start-up (power good going high) current charging C(PG) will discharge C(OUT2). Therefore, C(PG) must not be larger than 0.1 $C_{(OUT2)}$ or the device will not start. By charging $C_{(PG)}$ through $C_{(OUT2)}$, the output voltage at OUT2 will decrease. If the capacitance of C(PG) is to large, the circuit will detect power bad. The power-good output will go low and discharge C(PG). Then the cycle starts again. Figure 22 shows a configuration with an LC-post filter to further reduce output ripple and noise.

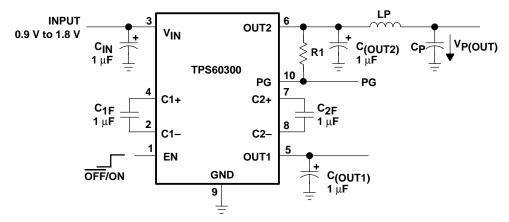


Figure 22. LC-Post Filter

IO(OUT2) [mA]		C _{IN} [μF]	C _{XF} [μF]	C _{OUT} [μF]	L_Ρ[μ H]	C_P[μ F]	V _P (OUT)
		CERAMIC	CERAMIC	CERAMIC		CERAMIC	V _{P-P} [mV]
	20	1.0	1.0	1.0	0.1	0.1 (X7R)	16

1.0

1.0

10

0.1

1.0

1.0

1 // 0.1 (X7R)

0.1 (X7R)

1 // 0.1 (X7R)

1.0

1.0

1.0

12

14

3



VIN

[V]

0.9...1.8

0.9...1.8

0.9...1.8

0.9...1.8

20

20

20

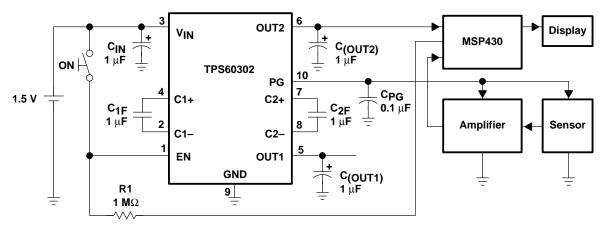
1.0

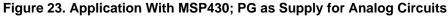
1.0

1.0

SLVS302A - DECEMBER 2000 - REVISED MARCH 2001

design procedure (continued)





power dissipation

As given in the data sheet, the thermal resistance of the unsoldered package is $R_{\theta JA} = 294^{\circ}C/W$. Soldered on the EVM, a typical thermal resistance of $R_{\theta JA(EVM)} = 200^{\circ}C/W$ was measured.

The thermal resistance can be calculated as follows:

$$\mathsf{R}_{\theta \mathsf{J}\mathsf{A}} = \frac{\mathsf{T}_{\mathsf{J}} - \mathsf{T}_{\mathsf{A}}}{\mathsf{P}_{\mathsf{D}}}$$

Where:

 T_J is the junction temperature. T_A is the ambient temperature. P_D is the power that needs to be dissipated by the device.

The maximum power dissipation can be calculated with the following formula:

 $P_{D} = V_{IN} \times I_{IN} - V_{O} \times I_{O} = V_{IN(max)} \times (3 \times I_{O} + I_{(SUPPLY)}) - V_{O} \times I_{O}$

The maximum power dissipation happens with maximum input voltage and maximum output current:

At maximum load the supply current is approximately 2 mA.

 $P_D = 1.8 \text{ V} \times (3 \times 20 \text{ mA} + 2 \text{ mA}) - 3.3 \text{ V} \times 20 \text{ mA} = 46 \text{ mW}.$

With this maximum rating and the thermal resistance of the device on the EVM, the maximum temperature rise above ambient temperature can be calculated:

 $\Delta T_J = R_{\theta JA} \times P_D = 200^{\circ}C/W \times 46 \text{ mW} = 10^{\circ}C$

This means that internal dissipation increases T_J by 10°C.

The junction temperature of the device must not exceed 125°C.

This means the IC can easily be used at ambient temperatures up to:

 $T_A = T_{J(max)} - \Delta T_J = 125^{\circ}C - 10^{\circ}C = 115^{\circ}C$

layout and board space

All capacitors should be soldered as close as possible to the IC. A PCB layout proposal for a two-layer board is shown in Figure 24. Care has been taken to connect all capacitors as close as possible to the circuit to achieve optimized output voltage ripple performance. The bottom layer is not shown in Figure 24. It only consists of a ground-plane with a single track between the two vias that can be seen in the left part of the top layer.



SLVS302A – DECEMBER 2000 – REVISED MARCH 2001

layout and board space (continued)

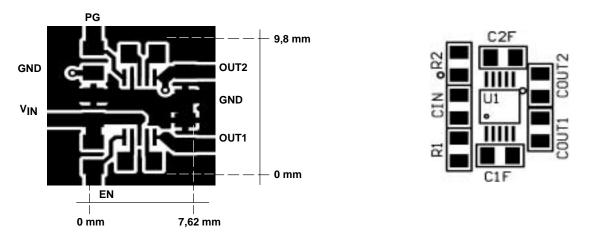


Figure 24. Recommended PCB Layout for TPS6030x (top layer)

device family products

Other charge pump dc-dc converters in this family are:

Table 5. Product Identification

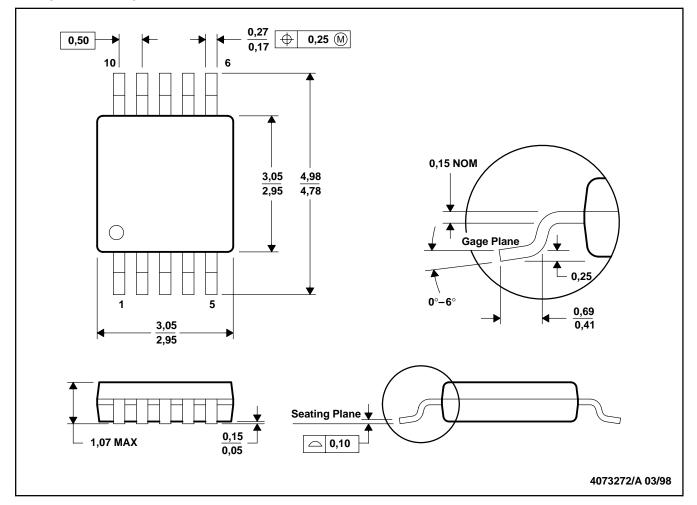
PART NUMBER	DESCRIPTION
TPS60100	2-cell to regulated 3.3-V, 200-mA low-noise charge pump
TPS60101	2-cell to regulated 3.3-V, 100-mA low-noise charge pump
TPS60110	3-cell to regulated 5-V, 300-mA low-noise charge pump
TPS60111	3-cell to regulated 5-V, 150-mA low-noise charge pump
TPS60120	2-cell to regulated 3.3-V, 200-mA high efficiency charge pump with low-battery comparator
TPS60121	2-cell to regulated 3.3-V, 200-mA high efficiency charge pump with power-good comparator
TPS60122	2-cell to regulated 3.3-V, 100-mA high efficiency charge pump with low-battery comparator
TPS60123	2-cell to regulated 3.3-V, 100-mA high efficiency charge pump with power-good comparator
TPS60124	2-cell to regulated 3-V, 200-mA high efficiency charge pump with low-battery comparator
TPS60125	2-cell to regulated 3-V, 200-mA high efficiency charge pump with power-good comparator
TPS60130	3-cell to regulated 5-V, 300-mA high efficiency charge pump with low-battery comparator
TPS60131	3-cell to regulated 5-V, 300-mA high efficiency charge pump with power-good comparator
TPS60132	3-cell to regulated 5-V, 150-mA high efficiency charge pump with low-battery comparator
TPS60133	3-cell to regulated 5-V, 150-mA high efficiency charge pump with power-good comparator
TPS60140	2-cell to regulated 5-V, 100-mA charge pump voltage tripler with low-battery comparator
TPS60141	2-cell to regulated 5-V, 100-mA charge pump voltage tripler with power-good comparator
TPS60200	2-cell to regulated 3.3-V, 100-mA low-ripple charge pump with low-battery comparator in MSOP10
TPS60201	2-cell to regulated 3.3-V, 100-mA low-ripple charge pump with power-good comparator in MSOP10
TPS60202	2-cell to regulated 3.3-V, 50-mA low-ripple charge pump with low-battery comparator in MSOP10
TPS60203	2-cell to regulated 3.3-V, 50-mA low-ripple charge pump with power-good comparator in MSOP10
TPS60210	2-cell to regulated 3.3-V, 100-mA low-ripple charge pump with ultralow operating current and low-battery comparator in MSOP10
TPS60211	2-cell to regulated 3.3-V, 100-mA low-ripple charge pump with ultralow operating current and power-good comparator in MSOP10
TPS60212	2-cell to regulated 3.3-V, 100-mA low-ripple charge pump with ultralow operating current and low-battery comparator in MSOP10
TPS60213	2-cell to regulated 3.3-V, 50-mA low-ripple charge pump with ultralow operating current and power-good comparator in MSOP10



SLVS302A - DECEMBER 2000 - REVISED MARCH 2001

MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

DGS (S-PDSO-G10)

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion.



TEXAS INSTRUMENTS

5-Oct-2007

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Packag Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TPS60300DGS	ACTIVE	MSOP	DGS	10	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS60300DGSG4	ACTIVE	MSOP	DGS	10	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS60300DGSR	ACTIVE	MSOP	DGS	10	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS60300DGSRG4	ACTIVE	MSOP	DGS	10	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS60301DGS	ACTIVE	MSOP	DGS	10	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS60301DGSG4	ACTIVE	MSOP	DGS	10	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS60301DGSR	ACTIVE	MSOP	DGS	10	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS60301DGSRG4	ACTIVE	MSOP	DGS	10	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS60302DGS	ACTIVE	MSOP	DGS	10	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS60302DGSG4	ACTIVE	MSOP	DGS	10	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS60302DGSR	ACTIVE	MSOP	DGS	10	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS60302DGSRG4	ACTIVE	MSOP	DGS	10	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS60303DGS	ACTIVE	MSOP	DGS	10	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS60303DGSG4	ACTIVE	MSOP	DGS	10	80	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS60303DGSR	ACTIVE	MSOP	DGS	10	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TPS60303DGSRG4	ACTIVE	MSOP	DGS	10	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)



⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

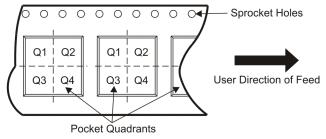
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

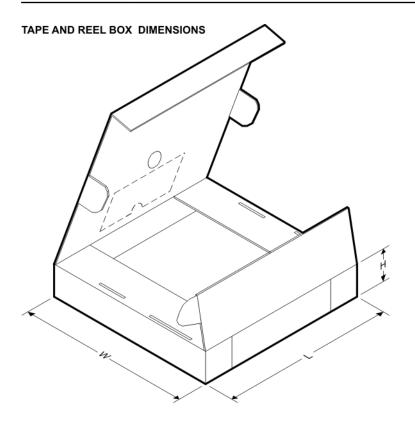


*All dimensions are nominal												
Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS60300DGSR	MSOP	DGS	10	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TPS60301DGSR	MSOP	DGS	10	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TPS60302DGSR	MSOP	DGS	10	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
TPS60303DGSR	MSOP	DGS	10	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1



PACKAGE MATERIALS INFORMATION

29-Jul-2008



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS60300DGSR	MSOP	DGS	10	2500	340.5	338.1	20.6
TPS60301DGSR	MSOP	DGS	10	2500	340.5	338.1	20.6
TPS60302DGSR	MSOP	DGS	10	2500	346.0	346.0	29.0
TPS60303DGSR	MSOP	DGS	10	2500	340.5	338.1	20.6

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive
DSP	dsp.ti.com	Broadband	www.ti.com/broadband
Clocks and Timers	www.ti.com/clocks	Digital Control	www.ti.com/digitalcontrol
Interface	interface.ti.com	Medical	www.ti.com/medical
Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
RFID	www.ti-rfid.com	Telephony	www.ti.com/telephony
RF/IF and ZigBee® Solutions	www.ti.com/lprf	Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2008, Texas Instruments Incorporated